

POWER MODULES THERMAL MANAGEMENT

MAKING YOUR POWER MODULE
REALIABLE AND THERMALLY BEST



DISIPA
HEAT S.L

C/PENEDES 47
POL. IND. CAN CASABLANQUES
08192 SANT QUIRZE DEL VALLES
TEL. (34)935115052 www.disipa.net

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HALA THERMAL INTERFACE SOLUTIONS

Phase Change

Films

- TPC-Z-PC
- TPC-T-AL-CB
- TPC-S-AL

Printable

- TPC-Z-PC-P
- TPC-X-PC-NC

Dispensable

- TPC-Z-PC-D

Graphite foil

- TFO-S-CB

Silicone foil

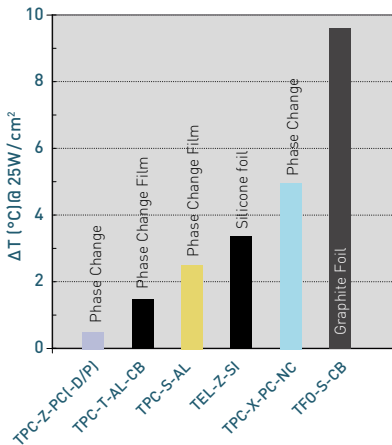
- TEL-Z-SI

Please contact us as your development partner.

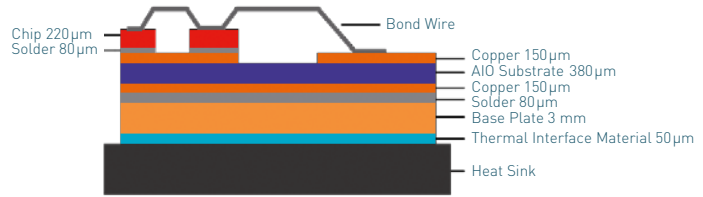


infineon Module EconoPACK™+

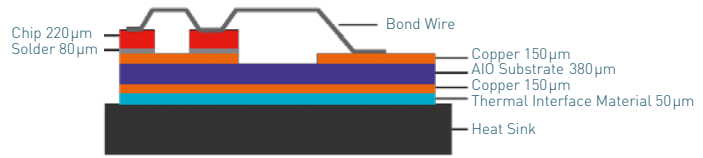
ΔT DATA



CONSTRUCTION DIAGRAM



Typical module configuration with baseplate (Copper)



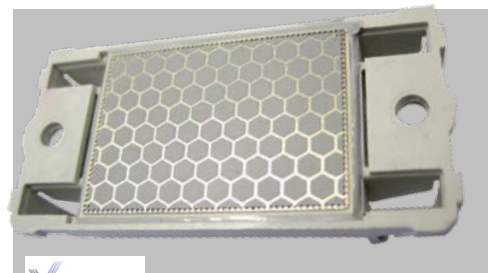
Typical module configuration without baseplate

CREATING

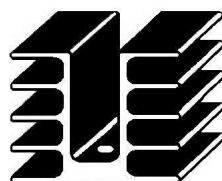
- Maximum thermal contact
- Minimized thermal resistance
- Compensating mechanic tolerances
- Enhancing efficiency

BENEFITS

- Increasing long-term reliability
- Minimizing chip temperatures
- Homogenizing chip temperatures
- Pre-applied dry-to-the-touch



Vincotech Module



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